

# i.MX 6 and i.MX 7 Series Comparison Table

i.MX applications processors are multicore ARM®-based solutions for multimedia and display applications with scalability, high performance, and low power capabilities.

| Features  | i.MX 6QuadPlus / i.MX 6DualPlus  | i.MX 6Quad / i.MX 6Dual  | i.MX 6DualLite   | i.MX 6Solo   | i.MX 6SoloX  | i.MX 6SoloLite   | i.MX 6UltraLite   | i.MX 6ULL   | i.MX 7Solo  | i.MX 7Dual  |
|---|--|--|--|--|--|--|---|---|---|---|
| CPU   | (i.MX 6QuadPlus) 4 x Cortex®-A9<br>(i.MX 6DualPlus) 2 x Cortex-A9  | (i.MX 6Quad) 4 x Cortex-A9<br>(i.MX 6Dual) 2 x Cortex-A9   | 2 x Cortex-A9  | Cortex-A9  | Cortex-A9, Cortex-M4   | Cortex-A9  | Cortex-A7   | Cortex-A7   | Cortex-A7, Cortex-M4  | 2 x Cortex-A7, Cortex-M4  |
| Maximum CPU Frequency                                   | 1.2 GHz  | 1.2 GHz  | 1 GHz  | 1 GHz  | (A9) 1 GHz (M4) 227 MHz  | 1 GHz  | 696 MHz   | 528 MHz   | (A7) 800 MHz (M4) 200 MHz   | (A7) 1.2 GHz (M4) 200 MHz   |
| I-Cache/D-Cache   | 32 KB/32 KB L1, 1 MB L2  | 32 KB/32 KB L1, 1 MB L2  | 32 KB/32 KB L1, 512 KB L2  | 32 KB/32 KB L1, 512 KB L2  | (A9) 32 KB/32 KB L1, 256 KB L2<br>(M4) 16 KB/16 KB L1  | 32 KB/32 KB L1, 256 KB L2  | 32 KB/32 KB L1, 128 KB L2*  | 32 KB/32 KB L1, 128 KB L2*                                      | (A7) 32 KB/32 KB L1, 512 KB L2<br>(M4) 16 KB/16 KB L1   | (A7) 32 KB/32 KB L1, 512 KB L2<br>(M4) 16 KB/16 KB L1   |
| Embedded SRAM   | 512 KB   | 256 KB   | 128 KB   | 128 KB   | 128 KB   | 128 KB   | 128 KB  | 128 KB  | 256 KB  | 256 KB  |
| External Memory Interface and DDR Bus Speed             | 2 x 32 LP-DDR2, 1-ch. x 64 DDR3/DDR3L, page and channel interleaving at up to 528 MHz, rawNAND   | 2 x 32 LP-DDR2, 1-ch. x 64 DDR3/DDR3L, page and channel interleaving at up to 528 MHz, rawNAND   | 2 x 32 LP-DDR2, 1-ch. x 64 DDR3/DDR3L page and channel interleaving at 400 MHz, rawNAND  | 1 x 32 LP-DDR2, DDR3/DDR3L page and channel interleaving at 400 MHz, rawNAND   | 1 x 32 LP-DDR2, DDR3/DDR3L page and channel interleaving at 400 MHz, rawNAND, QuadSPI NOR  | 1 x 32 LP-DDR2, DDR3/DDR3L at 400 MHz  | 1 x 16 LP-DDR2, DDR3/DDR3L at 400 MHz, rawNAND, QuadSPI NOR   | 1 x 16 LP-DDR2, DDR3/DDR3L at 400 MHz, rawNAND, QuadSPI NOR     | 32/16-bit LP-DDR2, DDR3, DDR3L, and LPDDR3 up to 533 MHz, rawNAND, QuadSPI NOR  | 32/16-bit LP-DDR2, DDR3, DDR3L, and LPDDR3 up to 533 MHz, rawNAND, QuadSPI NOR  |
| Display Interface                                       | HDMI + PHY, 2 x parallel, 2 x LVDS, MIPI DSI   | HDMI + PHY, 2x parallel, 2 x LVDS, MIPI DSI  | HDMI + PHY, 1 x parallel, 2 x LVDS, MIPI DSI, EPDC   | HDMI + PHY, 1 x parallel, 2 x LVDS, MIPI DSI, EPDC   | 1 x parallel, 1 x LVDS   | 1 x parallel, EPDC   | 1 x parallel*, touchscreen controller   | 1 x parallel*, touchscreen controller                           | 24-bit parallel RGB, MIPI DSI   | 24-bit parallel RGB, MIPI DSI, EPDC   |
| LCD Resolution  | 2 x QXGA (2048 x 1536) or 2 x WXGA (1280 x 720)  | 2 x QXGA (2048 x 1536) or 2 x WXGA (1280 x 720)  | 2 x WXGA (1280 x 720)  | 2 x WXGA (1280 x 720)  | 2 x WXGA (1280 x 720)*   | SXGA+ (1400 x 1050)  | WXGA (1366 x 768)*  | WXGA (1366 x 768)*  | 1080p (1920 x 1080), SXGA+ (1400 x 1050)  | 1080p (1920 x 1080), SXGA+ (1400 x 1050)  |
| Hardware Video Acceleration <sup>^</sup>                | HD (1080 + 720)p30 video decode, HD 1080p30 video encode   | HD (1080 + 720)p30 video decode, HD 1080p30 video encode   | HD (1080 + 720)p30 video decode, HD 1080p30 video encode   | HD1080p30 video decode, HD 1080p30 encode  | SW Only  | SW Only  | SW Only   | SW Only   | SW Only   | SW Only   |
| Hardware 2D/3D Graphics Acceleration                    | OpenGL® ES 1.1/2.0/3.0<br>OpenCL™ 1.1 EP,<br>OpenVG™ 1.1, 2DBLT, 8 layer composition, 4 shaders—720 MHz, embedded prefetch & resolve engine                                | OpenGL® ES 1.1/2.0/3.0<br>OpenCL™ 1.1 EP,<br>OpenVG™ 1.1, 2DBLT, 2 layer composition, 4 shaders—594 MHz  | OpenGL ES 1.1/2.0/3.0, OpenVG 1.1, 2DBLT, 2 layer composition, 1 shader—528 MHz  | OpenGL ES 1.1/2.0/3.0<br>OpenVG 1.1, 2DBLT, 1 shader—528 MHz   | OpenGL ES 1.1/2.0, OpenVG 1.1, 2DBLT, 1 shader—720 MHz   | OpenVG 1.1, 2DBLT 2 layer composition  | No, but has a Pxp*  | No, but has a Pxp*  | No, but has a Pxp*  | No, but has a Pxp*  |
| Camera Sensor Interface (CSI)                           | Parallel CSI, MIPI CSI   | Parallel CSI, MIPI CSI   | Parallel CSI, MIPI CSI   | Parallel CSI, MIPI CSI   | Parallel CSI, Analog   | Parallel CSI   | Parallel CSI*   | Parallel CSI*   | Parallel CSI, MIPI CSI  | Parallel CSI, MIPI CSI  |
| Universal Asynchronous Receiver/Transmitter (UART)      | 5  | 5  | 5  | 5  | 6  | 5  | 8*  | 8*  | 7   | 7   |
| Serial Peripheral Interface (SPI)/I <sup>2</sup> C      | 5/3  | 5/3  | 4/4  | 4/4  | 4/4  | 4/4  | 4/4*  | 4/4*  | 4/4   | 4/4   |
| USB Controller  | 1 x HS USB 2.0 OTG + PHY<br>1 x HS USB 2.0 Host + PHY<br>2 x HS USB 2.0 Host (HSIC)  | 1 x HS USB 2.0 OTG + PHY<br>1 x HS USB 2.0 Host + PHY<br>2 x HS USB 2.0 Host (HSIC)  | 1 x HS USB 2.0 OTG + PHY<br>1 x HS USB 2.0 Host + PHY<br>2 x HS USB 2.0 Host (HSIC)  | 1 x HS USB 2.0 OTG + PHY<br>1 x HS USB 2.0 Host + PHY<br>2 x HS USB 2.0 Host (HSIC)  | 2 x HS USB 2.0 OTG + PHY<br>1 x HS USB 2.0 Host (HSIC)   | 2 x HS USB 2.0 OTG + PHY<br>1 x HS USB 2.0 Host (HSIC)   | 2 x HS USB 2.0 OTG + PHY*   | 2 x HS USB 2.0 OTG + PHY*                                       | 1 x HS USB 2.0 OTG + PHY<br>1 x HS USB 2.0 Host (HSIC)  | 2 x HS USB 2.0 OTG + PHY<br>1 x HS USB 2.0 Host (HSIC)  |
| Power Management  | NXP MMPF0100   | NXP MMPF0100   | NXP MMPF0100   | NXP MMPF0100/MMPF0200  | NXP MMPF0100/MMPF0200  | NXP MMPF0100/MMPF0200  | Discrete  | Discrete  | NXP MC32PF3000/MC34PF3000   | NXP MC32PF3000/MC34PF3000   |
| Digital Audio Interface                                 | SSI/I <sup>2</sup> S x 3, ESAI, S/PDIF, ASRC   | SSI/I <sup>2</sup> S x 3, ESAI, S/PDIF, ASRC   | SSI/I <sup>2</sup> S x 3, ESAI, S/PDIF, ASRC   | SSI/I <sup>2</sup> S x 3, ESAI, S/PDIF, ASRC   | SSI/I <sup>2</sup> S x 5, ESAI, SAI, S/PDIF, ASRC  | SSI/I <sup>2</sup> S x 3, S/PDIF   | SAI/I <sup>2</sup> S x 3, S/PDIF, ASRC*   | SAI/I <sup>2</sup> S x 3, S/PDIF, ASRC*, ESAI x 1               | 3 x SAI   | 3 x SAI   |
| Ethernet  | 1 Gbit/s + IEEE® 1588  | 1 Gbit/s + IEEE 1588   | 1 Gbit/s + IEEE 1588   | 1 Gbit/s + IEEE 1588   | 2 x 1 Gbit/s + IEEE 1588 + AVB   | 10/100 Mbit/s  | 2 x 10/100 Mbit/s + IEEE 1588*  | 2 x 10/100 Mbit/s + IEEE 1588*                                  | 1 x Gbit w/AVB + IEEE 1588  | 2 x Gbit w/AVB + IEEE 1588  |
| PCI Express®  | PCIe® v2.0   | PCIe v2.0  | PCIe v2.0  | PCIe v2.0  | PCIe v2.0*   | No   | No  | No  | No  | PCIe v2.1   |
| CAN   | 2  | 2  | 2  | 2  | 2  | No   | 2*  | 2*  | 2   | 2   |
| Multimedia Card (eMMC)/Secure Digital Controller (SDIO) | 4 x eMMC 4.5 / SD 3.0  | 4 x eMMC 4.5 / SD 3.0  | 4 x eMMC 4.5 / SD 3.0  | 4 x eMMC 4.5 / SD 3.0  | 4 x eMMC 4.5 / SD 3.0  | 4 x eMMC 4.5 / SD 3.0  | 2 x eMMC 4.5 / SD 3.0   | 2 x eMMC 4.5 / SD 3.0   | 2 x eMMC 5.0 / SD 3.0   | 3 x eMMC 5.0 / SD 3.0   |
| Hard Disk Drive Interface                               | S-ATA II 3 Gbit/s  | S-ATA II 3 Gbit/s  | No   | No   | No   | No   | No  | No  | No  | No  |
| Smart Card Interface Module                             | No   | No   | No   | No   | No   | No   | Yes* (ISO7816-3)  | No  | 2   | 2   |
| Security  | Secure Boot, RNG, Tamper Detection, secure storage, AES-128, DES 3DES, ARC4, MD5, SHA-1, SHA-224, SHA-256, 16 KB Secure RAM, tamper-resistant RTC, secure debug, OTP Space | Secure Boot, RNG, Tamper Detection, secure storage, AES-128, DES 3DES, ARC4, MD5, SHA-1, SHA-224, SHA-256, 16 KB Secure RAM, tamper-resistant RTC, secure debug, OTP Space | Secure Boot, RNG, Tamper Detection, secure storage, AES-128, DES 3DES, ARC4, MD5, SHA-1, SHA-224, SHA-256, 16 KB Secure RAM, tamper-resistant RTC, secure debug, OTP Space | Secure Boot, RNG, Tamper Detection, secure storage, AES-128, DES 3DES, ARC4, MD5, SHA-1, SHA-224, SHA-256, 16 KB Secure RAM, tamper-resistant RTC, secure debug, OTP Space | Secure Boot, RNG, Tamper Detection, secure storage, AES-128, DES 3DES, ARC4, MD5, SHA-1, SHA-224, SHA-256, 16 KB Secure RAM, tamper-resistant RTC, secure debug, OTP Space | Secure Boot, tamper reaction, RNG, key storage, AES, DES, 3DES, ARC4, MD5, SHA-1, SHA-256, 128 KB Secure RAM, secure debug | Secure Boot, RNG, Tamper Detection, Secure Storage (including 32 KB Secure RAM), Cryptographic Accelerators (AES-128, DES 3DES, ARC4, MD5, SHA-1, SHA-224, SHA-256, RSA/ECDSA), Secure Debug, OTP Space | Secure Boot, RNG, AES-128                                       | ARM Trust Zone, Secure Boot, RNG, Tamper Detection, secure storage, AES-128, AES-256, DES, 3DES, ARC4, RSA (up to 4096), ECDSA, MD5, SHA-1, SHA-224, SHA-256, 32 KB Secure RAM, tamper-resistant RTC, secure debug, OTP Space | ARM Trust Zone, Secure Boot, RNG, Tamper Detection, secure storage, AES-128, AES-256, DES, 3DES, ARC4, RSA (up to 4096), ECDSA, MD5, SHA-1, SHA-224, SHA-256, 32 KB Secure RAM, tamper-resistant RTC, secure debug, OTP Space |
| Timer   | 3  | 3  | 3  | 3  | 3  | 3  | 4*  | 4*  | 2 x FlexTimer, 4 x GPT  | 2 x FlexTimer, 4 x GPT  |
| Real-Time Clock   | Secure RTC   | Secure RTC   | Secure RTC   | Secure RTC   | Secure RTC   | Secure RTC   | Secure RTC  | Secure RTC  | Secure RTC  | Secure RTC  |
| Pulse Width Modulation                                  | 4  | 4  | 4  | 4  | 8  | 4  | 8*  | 8*  | 4   | 4   |
| Package   | 21 x 21 BGA 0.8 mm pitch   | 21 x 21 BGA 0.8 mm pitch, POP <sup>#</sup>   | 21 x 21 BGA 0.8 mm pitch   | 21 x 21 BGA 0.8 mm pitch   | 14 x 14 BGA 0.65 mm pitch<br>17 x 17 BGA 0.8 mm pitch<br>19 x 19 BGA 0.8 mm pitch  | 13 x 13 BGA 0.5 mm pitch   | 14 x 14 289 BGA 0.8 mm pitch<br>9 x 9 289 BGA 0.5 mm pitch  | 14 x 14 289 BGA 0.8 mm pitch<br>9 x 9 289 BGA 0.5 mm pitch      | 12 x 12 BGA 0.4 mm pitch<br>19 x 19 BGA 0.75 mm pitch   | 12 x 12 BGA 0.4 mm pitch<br>19 x 19 BGA 0.75 mm pitch   |
| ADC Channels  | No   | No   | No   | No   | Yes*   | No   | Yes, Two 12-bit ADC, 1 with touch controller, up to 10 channel*   | Yes, Two 12-bit ADC, 1 with touch controller, up to 10 channel* | 2 x 12-bit ADC  | 2 x 12-bit ADC  |
| Qualifications  | Automotive, commercial and industrial  | Automotive, commercial and industrial  | Automotive, commercial and industrial  | Automotive, commercial and industrial  | Automotive, commercial and industrial  | Commercial   | Automotive, commercial and industrial   | Commercial and industrial                                       | Commercial and industrial   | Commercial and industrial   |

General Note1: Refer to IC documentation for specifications per processor.  
General Note 2: The number of interfaces is dependent on the pin muxing.

\* Some features vary across packages.

<sup>^</sup> Performance dependent on application use case.

<sup>#</sup> Refer to IC documentation for POP Package ARM and DDR frequencies and further details.

[www.nxp.com/iMX6Series](http://www.nxp.com/iMX6Series) and [www.nxp.com/iMX7Series](http://www.nxp.com/iMX7Series)

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